



GDZ8V2BLP3

ULTRA-SMALL LEADLESS SURFACE MOUNT ZENER DIODE

Features

- Ultra-Small Leadless Surface Mount Package (0.6 x 0.3mm)
- Ultra-Low Profile Package (0.3mm)
- Ideally Suited for Automated Assembly Processes
- Low Leakage Current, Suitable for Battery-Powered Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Notes 2 & 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: X3-DFN0603-2
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish Matte Tin over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.2 mg (Approximate)



Top View



Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
GDZ8V2BLP3-7	X3-DFN0603-2	10,000/Tape & Reel

Notes:

- 1. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free
- 2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

xx

xx = Product Marking Code (See Electrical Characteristics Table) Line Denotes Cathode Side



Thermal Characteristics

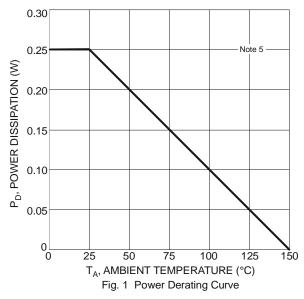
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) T _A = 25°C	P _D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5) T _A = 25°C	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

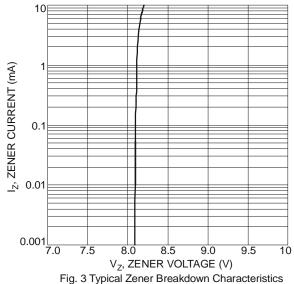
Electrical Characteristics @TA = 25°C unless otherwise specified

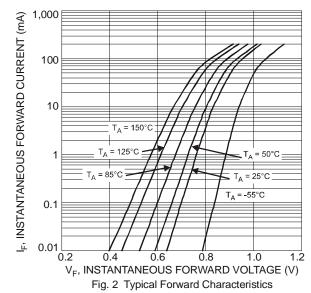
Type Number	Marking Code	Zener Voltage Range (Note 6)		Maximum Reverse Current (Note 6)			
		Vz @ IzT		@ V R			
		Nom (V)	Min (V)	Max (V)	mA	μΑ	V
GDZ8V2BLP3	KI, KR	8.2	7.995	8.405	5	0.5	5.0

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.







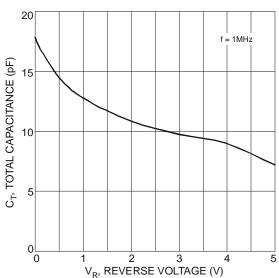
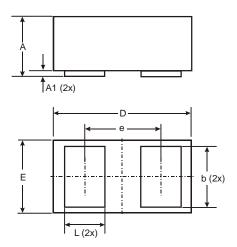


Fig. 4 Typical Total Capacitance

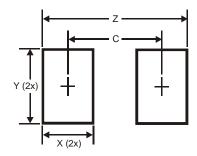


Package Outline Dimensions



X3-DFN0603-2			
Dim	Min	Max	Тур
Α	0.27	0.35	0.30
A1	0.00	0.03	0.02
b	0.19	0.29	0.24
D	0.595	0.645	0.62
Е	0.295	0.345	0.32
е	-	-	0.355
L	0.14	0.24	0.19
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
С	0.355
Х	0.230
Y	0.300
Z	0.610



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